



EXPEDITED PROCEDURE - EXAMINING GROUP 2812

S/N 09/253,611

6/3 (Ref)
J. Steptoe
1/9/01
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Examiner: Ron Pompey

Serial No.: 09/253,611

Group Art Unit: 2812

Filed: February 19, 1999

Docket: 303.572US1

Title: SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS

AMENDMENT & RESPONSE UNDER 37 C.F.R. § 1.116

Box AF
Commissioner for Patents
Washington, D.C. 20231

In response to the final Office Action mailed September 26, 2000, please amend the application as follows:

IN THE CLAIMS

Claims 1, 9, 12, 13 and 16 are amended hereinbelow. In addition, new claims 64-67 are added. As a result, claims 1-23 and 64-67 are pending.

Please amend claims 1, 9, 12, 13 and 16 as follows:

Sub
JAN 3 2001
B1
RECEIVED
TC 2800 MAIL ROOM

1. (Twice Amended) A method of forming a solder ball contact, comprising:
forming a metal contact pad on a substrate;
forming an insulating layer on the metal contact pad;
removing a portion of the insulating layer to expose a portion of the metal contact pad, thereby forming an exposed portion of the metal contact pad, the exposed portion having a predetermined diameter;
immersing the substrate in molten solder;
depositing solder on the exposed portion of the metal contact pad using selective deposition, thereby forming a solder contact; and
annealing the solder contact to form a solder ball contact having a diameter in a range of about 2.5 microns to no greater than 100 microns.